



Recommended PCB Layout

1. Material:

Contact: Copper Alloy

Insulator: LCP, UL94V-0

Shell: SPCC.

Harpoon: Copper Alloy

Rivet: Copper Alloy

2. Specification:

Contact Current Rating: 1 Amperes.

Dielectric Withstanding Voltage: AC 500V at sea level.

Insulation Resistance: 1000 Megohms Min.

Contact Resistance: 30m ohms Max.

Operation Temperature: -55°C to +105°C.

<b>RoHS Compliant</b>		<b>HSM 玄茂科技股份有限公司</b> <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准		<b>TOLERANCE</b> 容許公差 0 ± 0.35 .00 ± 0.25 ANG. ± 3°	<b>PART NAME 品名</b> D-SUB R/A FOR NOTE BOOK-9M W/O SCREWS NICKEL SHELL+DIMPLE SELECTIVE GOLD PLATED BLACK LAYOUT SINGLE ROW(24.99/15.9) MATERIAL:LCP ROHS
DWG. 製圖 <i>Helen</i>	<b>SCALE</b> 比例 參考	<b>UNIT</b> 單位 MM	<b>PART NO.</b> 料號 C0526-09MBABXBN
DATE 制表日 2020/8/6	<b>PAGE</b> 張數 1 OF 1	<b>SIZE</b> 紙張尺寸 A4	